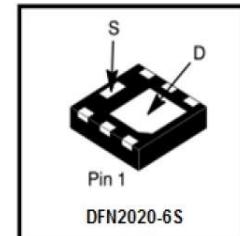


P3418D

30V P-Channel (D-S) MOSFET

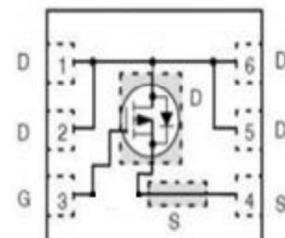
1. FEATURES

- VDS = -30V
RDS(ON)≤25mΩ ,VGS@-10V,IDS@-7.3A
RDS(ON)≤38mΩ,VGS@-4.5V,IDS@-5.9A
- Low RDS(ON) trench technology.
- Low thermal impedance.
- Fast switching speed.
- We declare that the material of product compliance with RoHS requirements and Halogen Free.



2. APPLICATIONS

- Load Switches
- DC/DC Conversion
- Motor Drives



3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
P3418D	3B1	4000/Tape&Reel

4. MAXIMUM RATINGS(Ta = 25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		VDS	-30	V
Gate-Source Voltage		VGS	± 20	
Continuous Drain Current(Note 1)		ID	-9.4	A
Pulsed Drain Current(Note 2)		IDM	-40	
Maximum Power Dissipation(Note 1)	TA = 25°C	PD	3.1	W
	TA = 70°C		2	
Operating Junction and Storage Temperature Range		TJ , Tstg	-50~+150	°C
Continuous Source Current (Diode Conduction)(Note 1)		IS	3.8	A

Note: 1. Surface Mounted on 1" x 1" FR4 Board.

2. Pulse width limited by maximum junction temperature.

5. THERMAL CHARACTERISTICS

Parameter		Symbol	Max	Unit
Maximum Junction-to-Ambient (Note 1)	t≤10S	RθJA	40	°C/W
	Steady State		90	



6. ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ C$)

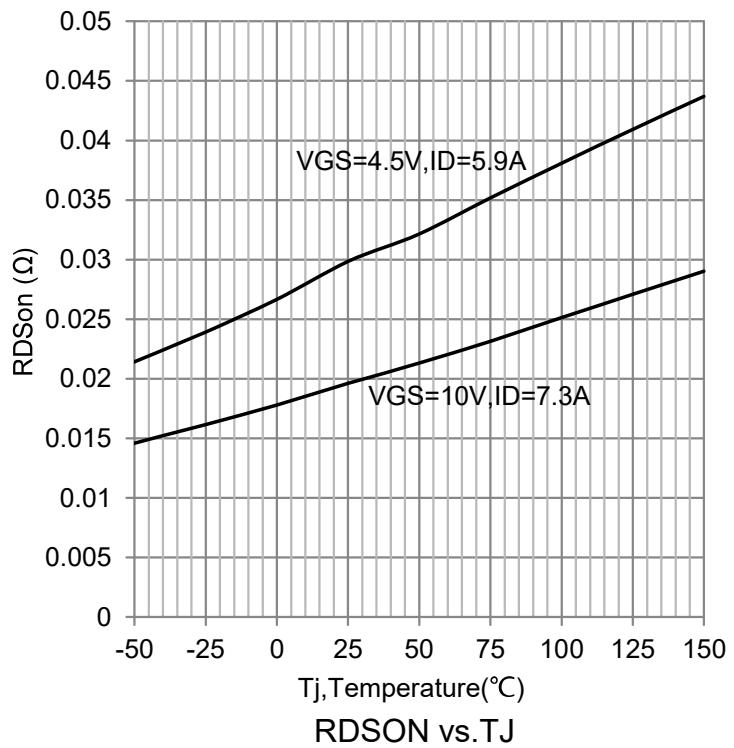
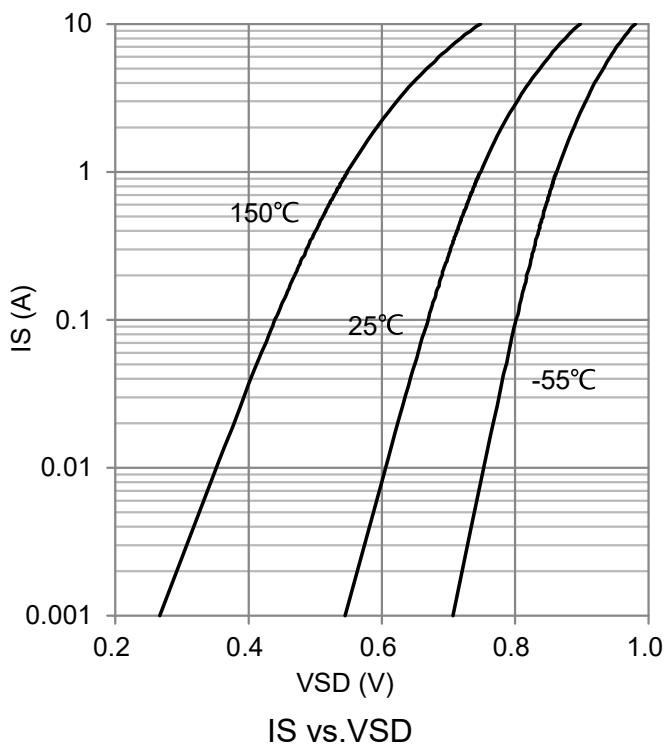
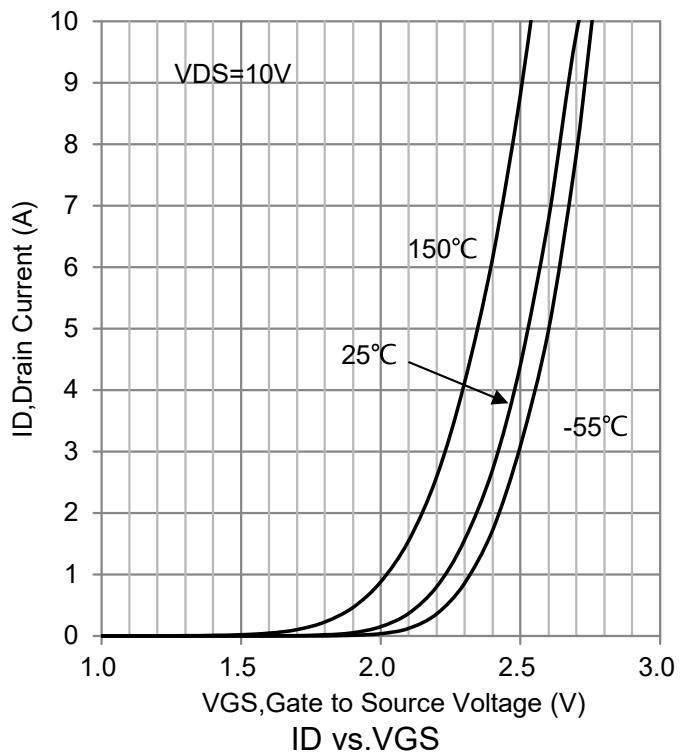
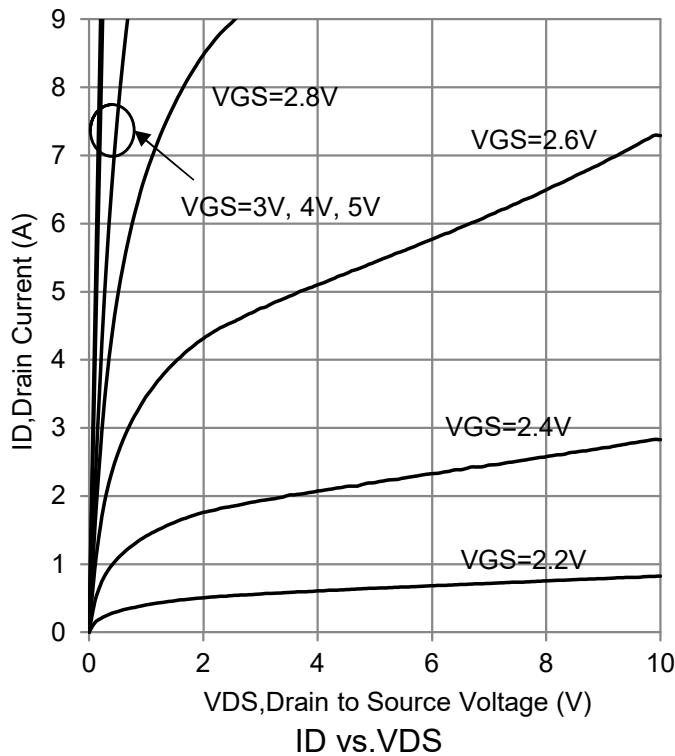
Characteristic	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain-Source Breakdown Voltage ($V_{GS} = 0V$, $ID = -250\mu A$)	$V(BR)DSS$	-30	-	-	V
Gate Threshold Voltage ($V_{DS} = V_{GS}$, $ID = -250\mu A$)	$V_{GS(th)}$	-1	-	-3	V
Gate Leakage Current ($V_{DS} = 0V$, $V_{GS} = \pm 20V$)	I_{GSS}	-	-	± 100	nA
Zero Gate Voltage Drain Current ($V_{DS} = -24V$, $V_{GS} = 0V$)	I_{DSS}	-	-	-1	μA
On-State Drain Current(Note 3) ($V_{DS} = -5 V$, $V_{GS} = -10 V$)	$I_{D(on)}$	-14	-	-	A
Drain-Source On-Resistance ($V_{GS} = -10V$, $ID = -7.3A$)	$R_{DS(ON)}$ (Note 3)	-	-	25	$m\Omega$
Drain-Source On-Resistance ($V_{GS} = -4.5V$, $ID = -5.9A$)		-	-	38	
Diode Forward Voltage(Note 3) ($I_S = -1A$, $V_{GS} = 0V$)	V_{SD}	-	-	-1.5	V
Forward Transconductance(Note 3) ($V_{DS} = -15 V$, $ID = -7.3 A$)	g_{fs}	-	10	-	S
DYNAMIC(Note 4)					
Total Gate Charge	$(V_{DS} = -15 V$, $V_{GS} = -4.5 V$, $ID = -7.3 A)$	Q_g	-	11.2	-
Gate-Source Charge		Q_{gs}	-	2.8	-
Gate-Drain Charge		Q_{gd}	-	4.2	-
Input Capacitance	$(V_{DS} = -15 V$, $V_{GS} = 0 V$, $f = 1$ MHz)	C_{iss}	-	1370	-
Output Capacitance		C_{oss}	-	133	-
Reverse Transfer Capacitance		C_{rss}	-	112	-
Turn-On Delay Time	$(V_{DS} = -15 V$, R_L $= 2.1 \Omega$, $ID = -7.3$ A, $V_{GEN} = -10$ V , $R_{GEN} = 6 \Omega$)	$t_{d(on)}$	-	6	-
Turn-On Rise Time		t_r	-	5	-
Turn-Off Delay Time		$t_{d(off)}$	-	55	-
Turn-Off Fall Time		t_f	-	21	-

Note: 3. Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

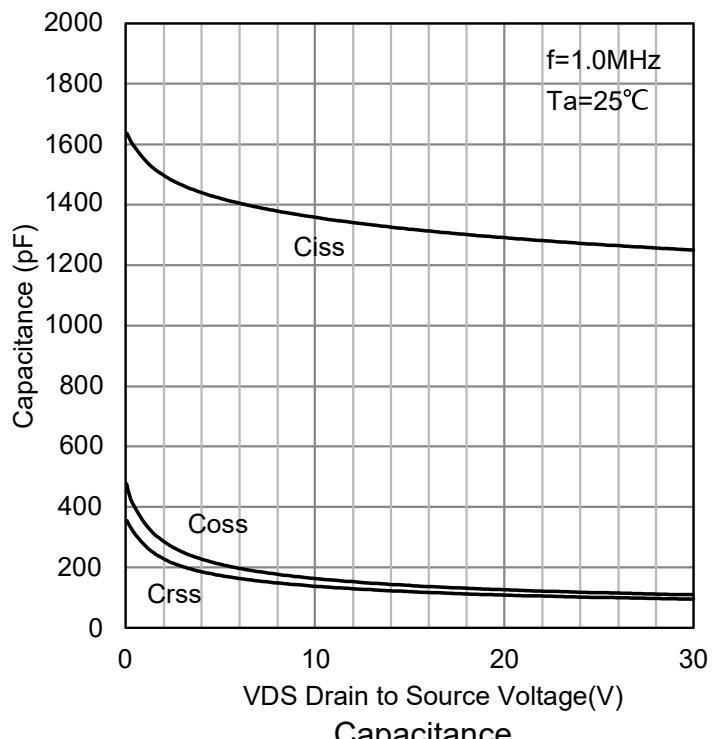
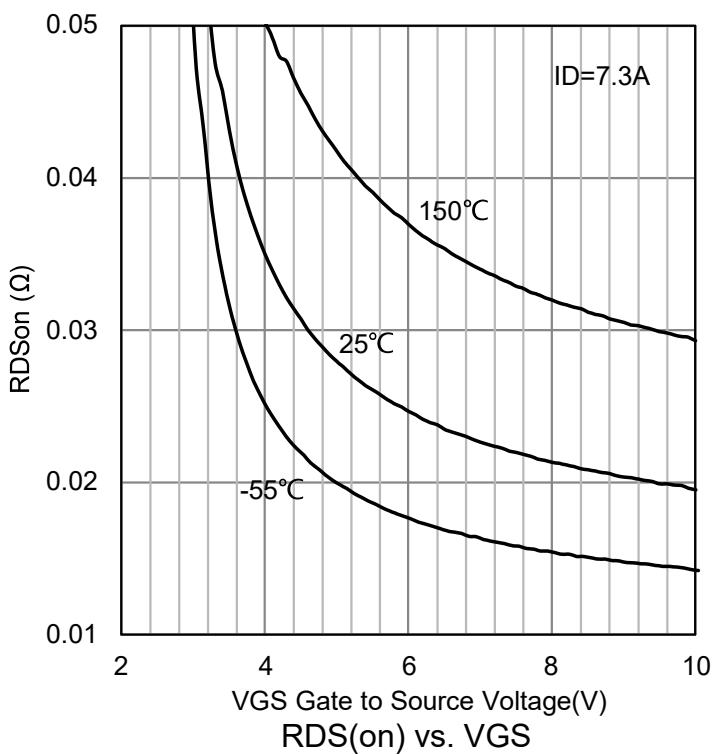
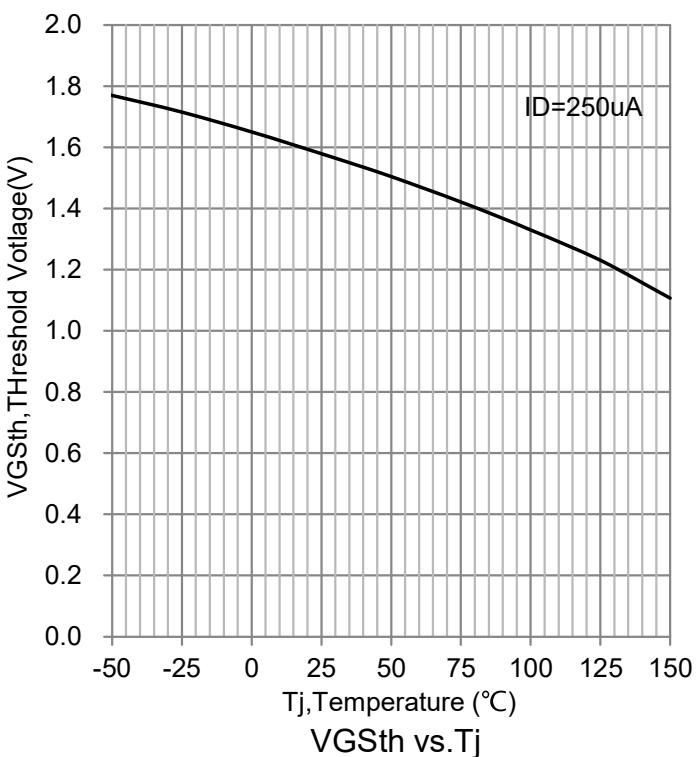
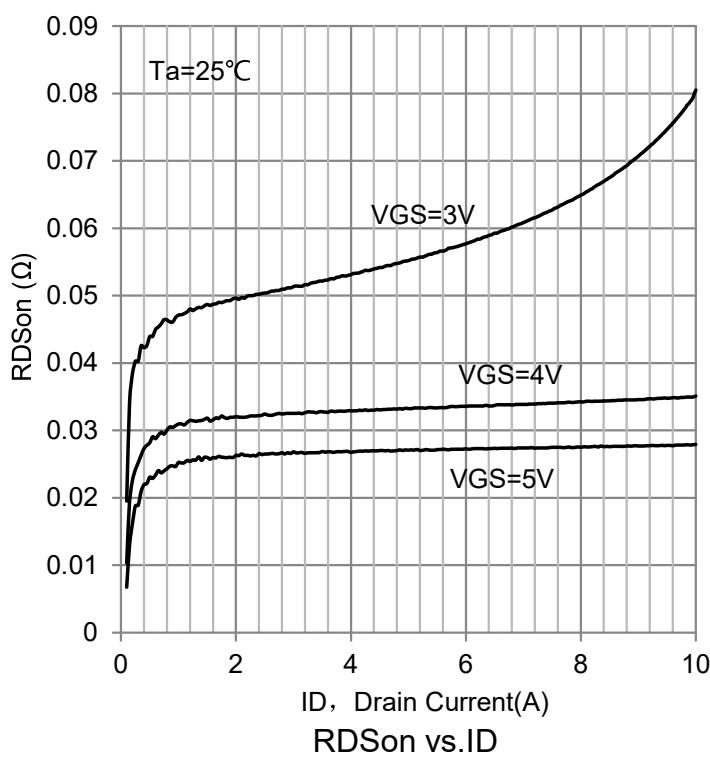
4. Guaranteed by design, not subject to production testing.



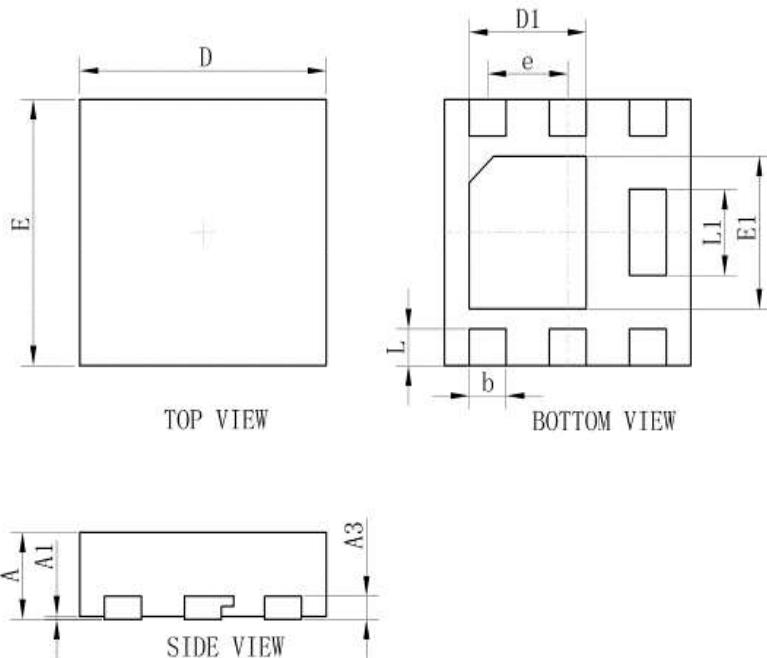
7. ELECTRICAL CHARACTERISTICS CURVES



7. ELECTRICAL CHARACTERISTICS CURVES(Con.)



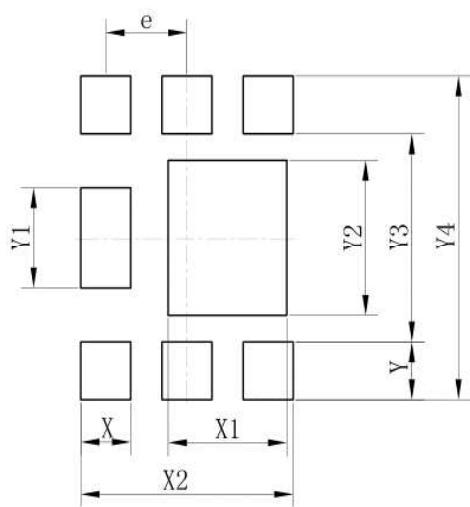
8. OUTLINE AND DIMENSIONS



DFN2020-6S			
DIM	MIN	NOR	MAX
A	0.60	0.65	0.70
A1	0.01	0.03	0.05
b	0.25	0.30	0.35
D	1.95	2.00	2.05
E	1.95	2.00	2.05
e	0.65TYP.		
L	0.23	0.28	0.33
L1	0.60	0.65	0.65
D1	0.90	0.95	1.00
E1	1.10	1.15	1.20
A3	0.152REF		

All Dimensions in mm

9. SOLDERING FOOTPRINT



DFN2020-6S	
Dim	(mm)
X	0.40
X1	0.95
X2	1.70
e	0.65
Y	0.43
Y1	0.75
Y2	1.15
Y3	1.54
Y4	2.39

